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Flexible Insulating Epoxy
Two Component Pastes
Thermally Conductive
Stress-Free Bonding
Available in Pre-mixed Form

IDEAL FOR:

- Heat-Sink Attach
- Substrate & Component Attaches
- Large Area Bonding
- Bonding Adherends with Mixmatched CTE's

DESCRIPTION:

EG7655 is a reworkable, alumina filled, electrically insulating and thermally conductive epoxy paste adhesive which exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper). EG7655's high thermal conductivity and flexibility make it excellent for bonding large area substrates, components and heat sinks where thermal management is critical.

EG7655 exhibits reduced bond strength at 80-100°C for easier rework. The cured adhesive is flexible with Type A hardness of 80 and tensile elongation of more than 30%.

AVAILABILITY:

EG7655 is available in syringes for automatic needle dispense applications or in jars. Upon request, the material can be shipped premixed and frozen.

APPLICATION PROCEDURES:

- (1) Store Part A and Part B at ambient.
- (2) Mix A and B 1:1 by weight. Part A has higher viscosity.
- (3) Cure according to one of the recommended schedules.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.
 The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

PRIMA-BOND
EG7655

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 60 minutes)	>1x10 ¹⁴ ohm-cm
Dielectric Strength (Volts/mil)	> 750
Glass Transition Temp.(°C)	-20 ±10%
Current Carrying Capabilities	N/A
Lap-Shear Strength	>1000 psi >6.9 N/mm ²
Device Push-off Strength	>1800 psi >12.4 N/mm ²
Cured Density (gm/cc)	2.3 ±10%
Thermal Conductivity	12 Btu-in/hr-ft ² -°F ±10% 1.7 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	140 ±10%
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(0.5 rpm, 25°C) (Brookfield DV-1, spindle CP51)	280,000 cp ±20%

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****CURE SCHEDULES:**

Temperature	Time
25°C	120 hr
80°C	8 hr
100°C	4 hr
125°C	2 hr
150°C	1 hr

**If the material is premixed and frozen thaw for 30 minutes, apply and cure according to one of the recommended cure schedules.
 ***Shelf life is for unmixed components. If premixed:-40°C for 6 months. After mixing, pot life is 4 hours at 25°C.

SHELF LIFE:

Storage temperature	Shelf Life
25°C	***1 yr